MSKSEMI 美森科













ESD

S

TSS -

MOV

GDT

PIFD

MS79L05S/MS79L05

Product specification





Maximum output current lo: 0.1 A

Output voltage Vo: -5 V

Continuous total dissipation

PD: SOT-23-3L 0.35 W (Ta= 25 $^{\circ}$ C)

SOT-89 0.5 W (Ta= 25 °C)

SOT-23	SOT-89	
	1 2	1.GND 2.OUT 3.IN

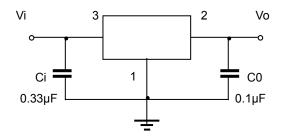
ABSOLUTE MAXIMUM RATINGS(Operating temperature range applies unless otherwise specified)

Parameter	Symbol	Value	Units
Input Voltage	Vi	-30	V
Operating Junction Temperature Range	T _{OPR}	0~+125	°C
Storage Temperature Range	Тѕтс	-55~+150	°C

ELECTRICAL CHARACTERISTICS AT SPECIFIED VIRTUAL JINCTION TEMPERATURE(VI=-10V,Io=40mA,Ci=0.33 μ F,Co=0.1 μ F, unless otherwise specified)

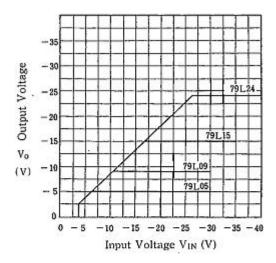
Parameter	Symbol	Test conditions		MIN	TYP	MAX	UNIT
			25℃	-4.8	-5.0	-5.2	V
Output voltage	Vo	-7V≤V ≤-20V, lo=1mA~40mA	0-125℃ ├──	-4.75	-5.0	-5.25	V
		lo=1mA~70mA		-4.75	-5.0	-5.25	V
Load Regulation	ΔVο	lo=1mA~100mA	25℃		20	60	mV
Load Negulation	Δνο	lo=1mA~40mA	25℃		10	30	mV
Line regulation	ΔVο	-7V≤V ≤-20V	25℃		15	150	mV
		-8V≤V ≤-20V	25℃		12	100	mV
Quiescent Current	lq		25℃			6	mA
Quiescent Current Change	Δlq	-8V≤V ≤-20V	0-125℃			1.5	mA
Quiescent Current Change	Δlq	1mA≤V ı≤40mA	0-125℃			0.1	mA
Output Noise Voltage	VN	10Hz≤f≤100KHz	25℃		40		uV
Ripple Rejection	RR	-8V≤V ≤-18V,f=120Hz	0-125℃	41	49		dB
Dropout Voltage	Vd		25℃		1.7		V

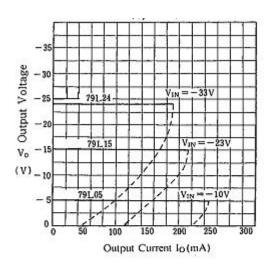
TYPICAL APPLICATION

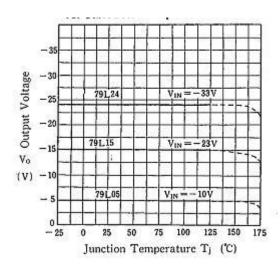


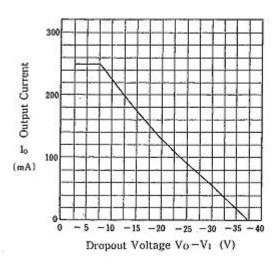
Note: Bypass capacitors are recommended for optimum stability and transient response and should be located as close as Possible to the regulators.

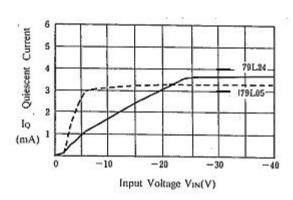
TypicalCharacteristics

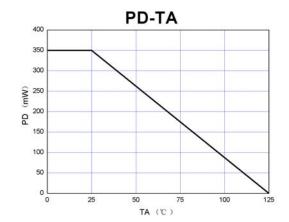






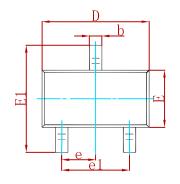


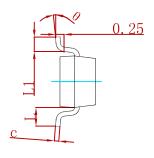


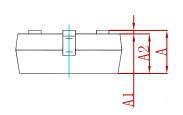




PACKAGE MECHANICAL DATA

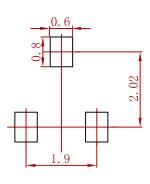






Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Min Max		Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037	7 TYP	
e1	1.800	2.000	0.071	0.079	
Ĺ	0.550 REF		0.022	2 REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



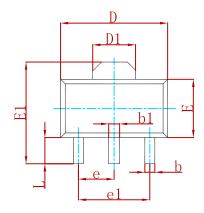
Note

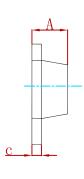
- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MS79L05S	SOT-23	3000

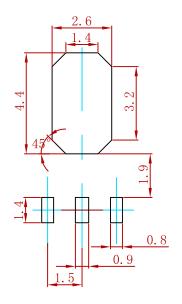
PACKAGE MECHANICAL DATA





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.400	1.600	0.055	0.063	
b	0.320	0.520	0.013	0.020	
b1	0.400	0.580	0.016	0.023	
С	0.350	0.440	0.014	0.017	
D	4.400	4.600	0.173	0.181	
D1	1.550 REF.		0.061 REF.		
E	2.300	2.600	0.091	0.102	
E1	3.940	4.250	0.155	0.167	
е	1.500 TYP.		0.060	TYP.	
e1	3.000	3.000 TYP.		TYP.	
L	0.900	1.200	0.035	0.047	

Suggested Pad Layout



Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MS79L05	SOT-89	1000



Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer'sproducts or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents—or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.